

DMN3730U

30V N-CHANNEL ENHANCEMENT MODE MOSFET IN SOT23

## Product Summary

$V_{(BR)DSS}$	Max $R_{DS(on)}$	$I_D$ Max (Note 5) $T_A = 25^\circ C$
30V	460m $\Omega$ @ $V_{GS} = 4.5V$	0.94A
	560m $\Omega$ @ $V_{GS} = 2.5V$	0.85A

## Description and Applications

This MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Load switch
- Portable applications
- Power Management Functions



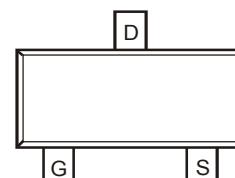
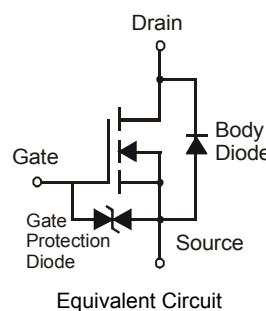
Top View

## Features and Benefits

- Low  $V_{GS(th)}$ , can be driven directly from a battery
- Low  $R_{DS(on)}$
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- ESD Protected Gate 2kV
- Qualified to AEC-Q101 Standards for High Reliability

## Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish-Matte Tin.
- Weight: 0.08 grams (approximate)


Top View  
Pin-Out

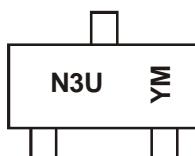
## Ordering Information (Note 3)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN3730U-7	N3U	7	8	3,000

Notes:

1. No purposefully added lead
2. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>.
3. For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



N3U = Product Type Marking Code  
YM = Date Code Marking  
Y = Year (ex: Y = 2011)  
M = Month (ex: 9 = September)

### Date Code Key

Year	2011	2012	2013	2014	2015	2016	2017					
Code	Y	Z	A	B	C	D	E					
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

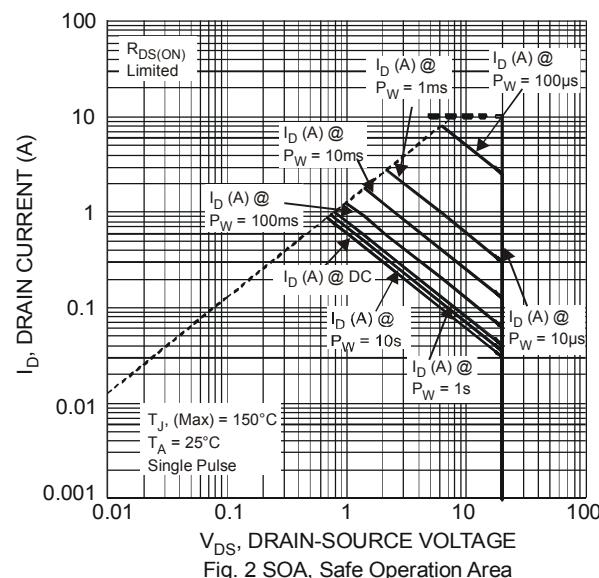
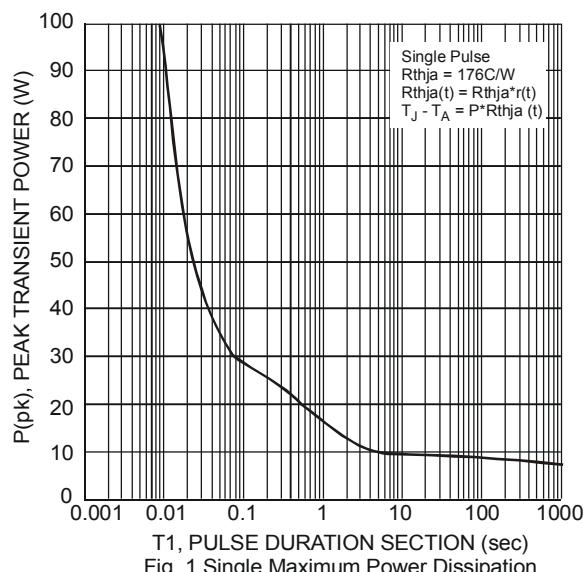
Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	$\pm 8$	V
Continuous Drain Current	Steady State	$T_A = 25^\circ\text{C}$ (Note 5) $T_A = 85^\circ\text{C}$ (Note 5) $T_A = 25^\circ\text{C}$ (Note 4)	$I_D$	0.94 0.68 0.75	A
Pulsed Drain Current (Note 6)			$I_{DM}$	10	A

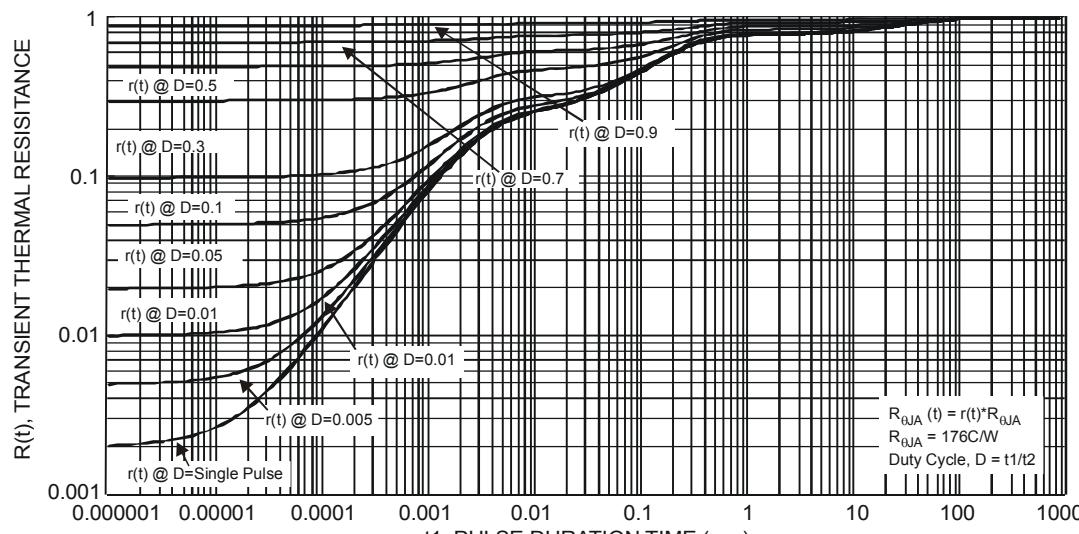
**Thermal Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 4)	$P_D$	0.45	W
	(Note 5)		0.71	W
Thermal Resistance, Junction to Ambient	(Note 4)	$R_{\theta JA}$	275	$^\circ\text{C}/\text{W}$
	(Note 5)		177	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

Notes:

4. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout
5. Device mounted on 25mm X 25mm square copper plate with FR-4 substrate PC board, 2oz copper
6. Device mounted on minimum recommended pad layout test board, 10 $\mu\text{s}$  pulse duty cycle = 1%.

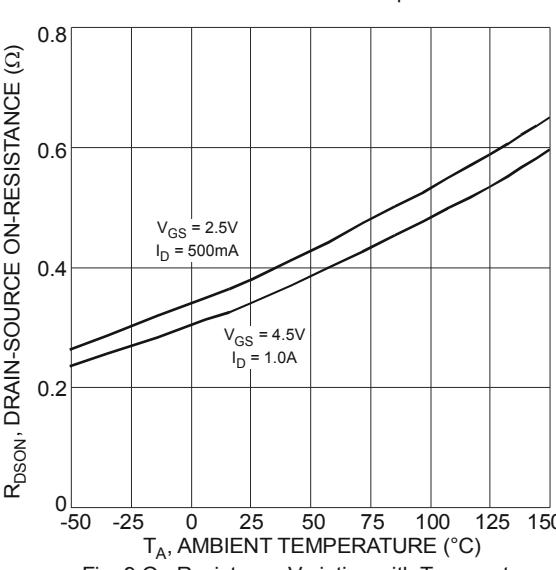
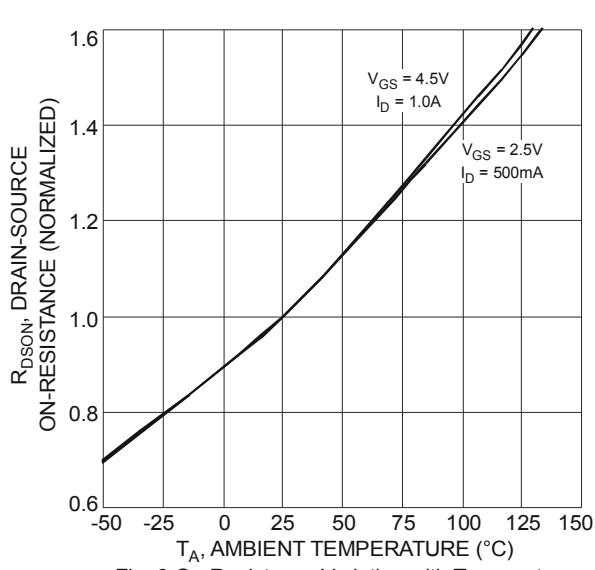
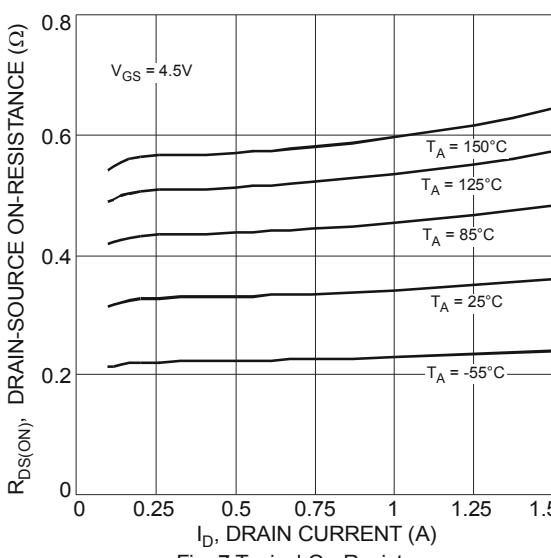
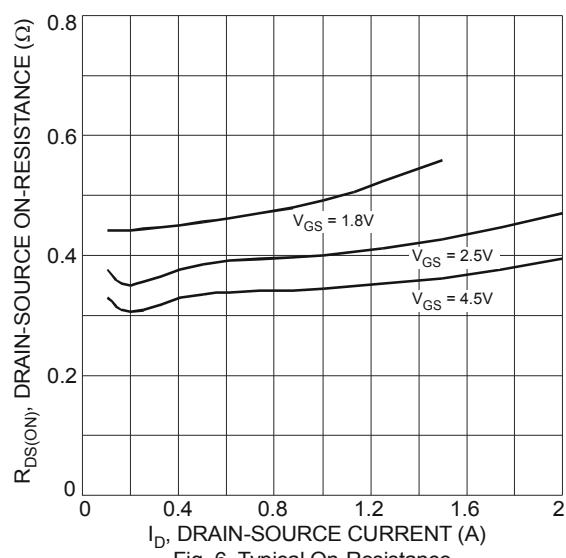
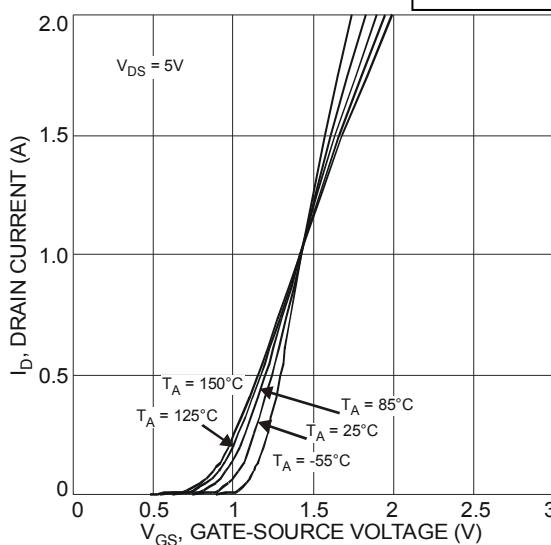
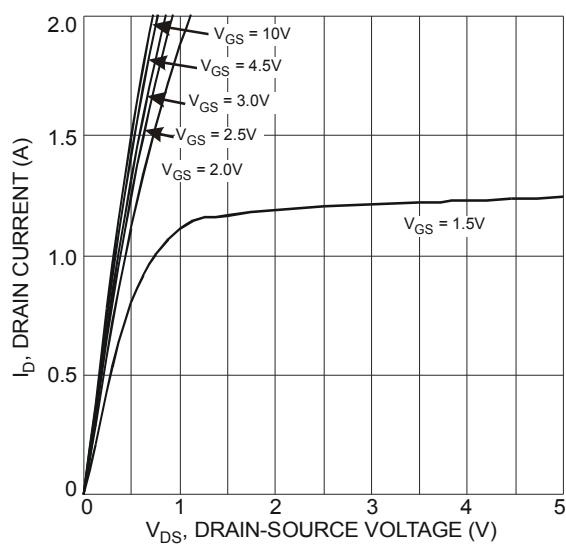
**Thermal Characteristics**



**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	30	-	-	V	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{I}_D = 10\mu\text{A}$
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	-	-	1	$\mu\text{A}$	$\text{V}_{\text{DS}} = 30\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$
Gate-Source Leakage	$\text{I}_{\text{GSS}}$	-	-	3	$\mu\text{A}$	$\text{V}_{\text{GS}} = \pm 8\text{V}$ , $\text{V}_{\text{DS}} = 0\text{V}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	0.45	-	0.95	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$ , $\text{I}_D = 250\mu\text{A}$
Static Drain-Source On-Resistance (Note 7)	$\text{R}_{\text{DS(on)}}$	-	-	460	$\text{m}\Omega$	$\text{V}_{\text{GS}} = 4.5\text{V}$ , $\text{I}_D = 200\text{mA}$
				560		$\text{V}_{\text{GS}} = 2.5\text{V}$ , $\text{I}_D = 100\text{mA}$
				730		$\text{V}_{\text{GS}} = 1.8\text{V}$ , $\text{I}_D = 75\text{mA}$
Forward Transfer Admittance	$ \text{Y}_{\text{fs}} $	40	-	-	$\text{mS}$	$\text{V}_{\text{DS}} = 3\text{V}$ , $\text{I}_D = 10\text{mA}$
Diode Forward Voltage (Note 7)	$\text{V}_{\text{SD}}$	-	0.7	1.2	V	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{I}_S = 300\text{mA}$
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	-	64.3	-	$\text{pF}$	$\text{V}_{\text{DS}} = 25\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$ , $f = 1.0\text{MHz}$
Output Capacitance	$\text{C}_{\text{oss}}$	-	6.1	-	$\text{pF}$	
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$	-	4.5	-	$\text{pF}$	
Gate Resistance	$\text{R}_{\text{g}}$	-	70	-	$\Omega$	$\text{V}_{\text{DS}} = 0\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$ , $f = 1\text{MHz}$
Total Gate Charge	$\text{Q}_{\text{g}}$	-	1.6	-	$\text{nC}$	$\text{V}_{\text{GS}} = 4.5\text{V}$ , $\text{V}_{\text{DS}} = 15\text{V}$ , $\text{I}_D = 1\text{A}$
Gate-Source Charge	$\text{Q}_{\text{gs}}$	-	0.2	-	$\text{nC}$	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$	-	0.2	-	$\text{nC}$	
Turn-On Delay Time	$\text{t}_{\text{D(on)}}$	-	3.5	-	$\text{ns}$	$\text{V}_{\text{DS}} = 10\text{V}$ , $\text{I}_D = 1\text{A}$
Turn-On Rise Time	$\text{t}_{\text{r}}$	-	2.8	-	$\text{ns}$	
Turn-Off Delay Time	$\text{t}_{\text{D(off)}}$	-	38	-	$\text{ns}$	
Turn-Off Fall Time	$\text{t}_{\text{f}}$	-	13	-	$\text{ns}$	

Notes: 7. Measured under pulsed conditions to minimize self-heating effect. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$

8. For design aid only, not subject to production testing.



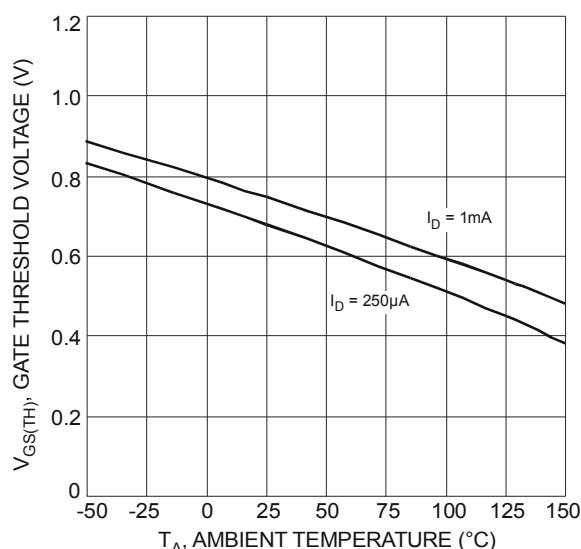


Fig. 10 Gate Threshold Variation vs. Ambient Temperature

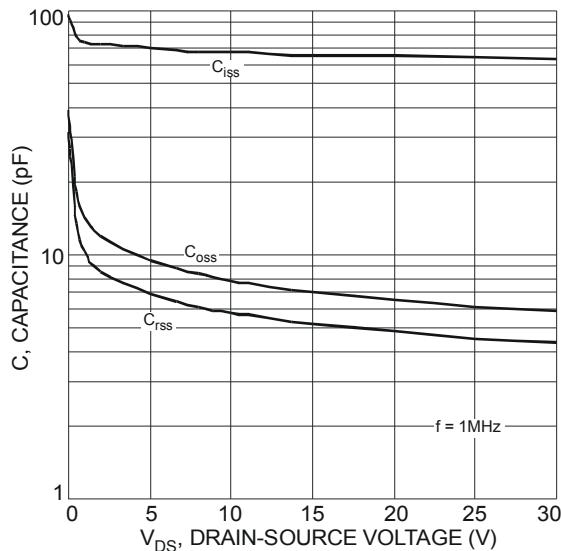


Fig. 12 Typical Total Capacitance

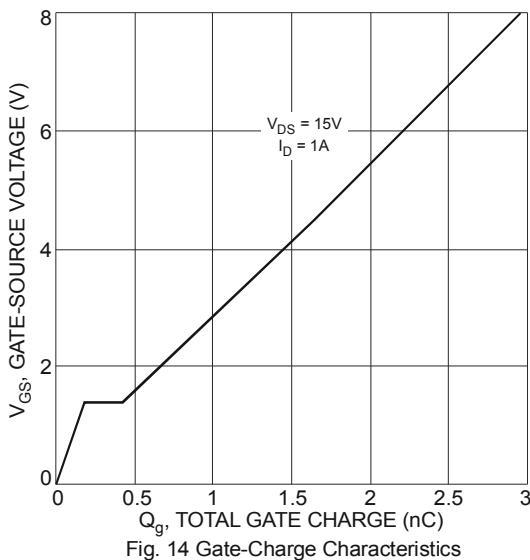


Fig. 14 Gate-Charge Characteristics

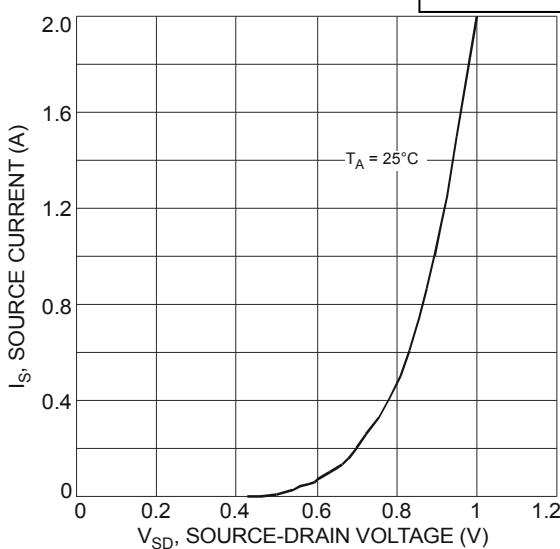


Fig. 11 Diode Forward Voltage vs. Current

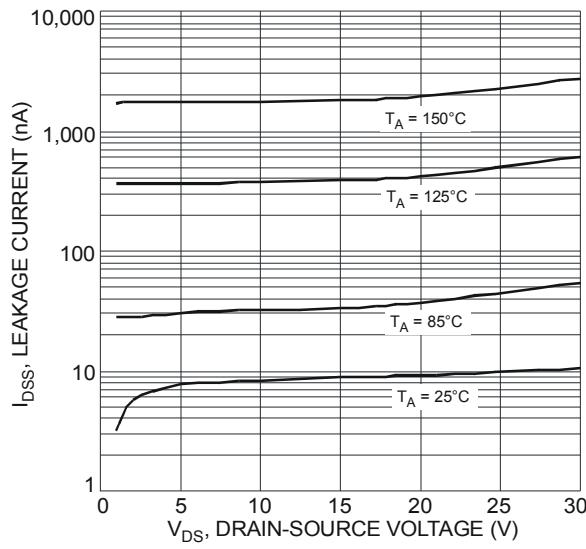
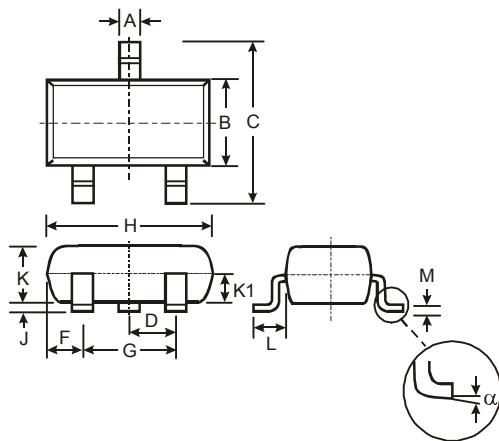


Fig. 13 Typical Leakage Current vs. Drain-Source Voltage

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## Package Outline Dimensions

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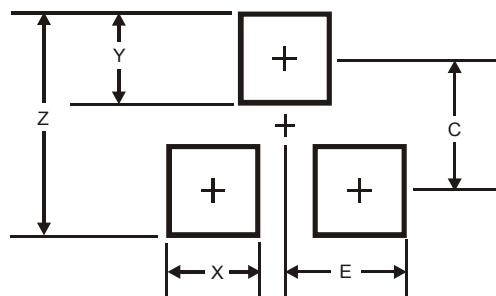
SOT23			
Dim	Min	Max	Typ
<b>A</b>	0.37	0.51	0.40
<b>B</b>	1.20	1.40	1.30
<b>C</b>	2.30	2.50	2.40
<b>D</b>	0.89	1.03	0.915
<b>F</b>	0.45	0.60	0.535
<b>G</b>	1.78	2.05	1.83
<b>H</b>	2.80	3.00	2.90
<b>J</b>	0.013	0.10	0.05
<b>K</b>	0.903	1.10	1.00
<b>K1</b>	-	-	0.400
<b>L</b>	0.45	0.61	0.55
<b>M</b>	0.085	0.18	0.11
$\alpha$	0°	8°	-

All Dimensions in mm

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## Suggested Pad Layout

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Dimensions	Value (in mm)
<b>Z</b>	2.9
<b>X</b>	0.8
<b>Y</b>	0.9
<b>C</b>	2.0
<b>E</b>	1.35

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